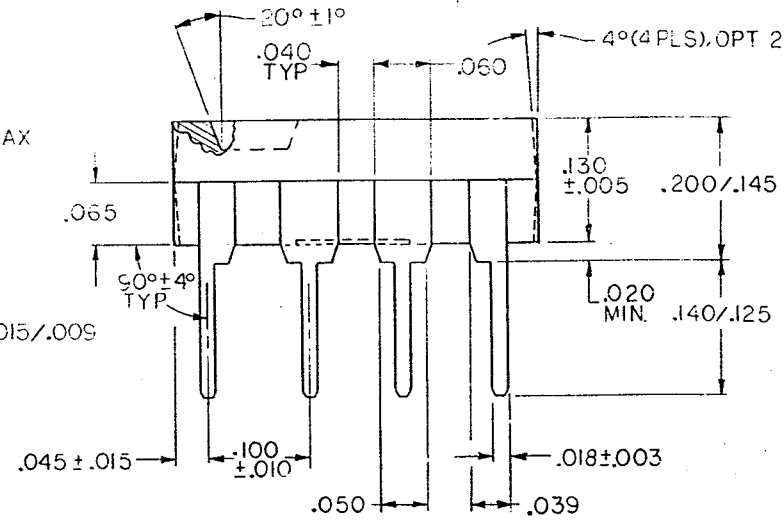
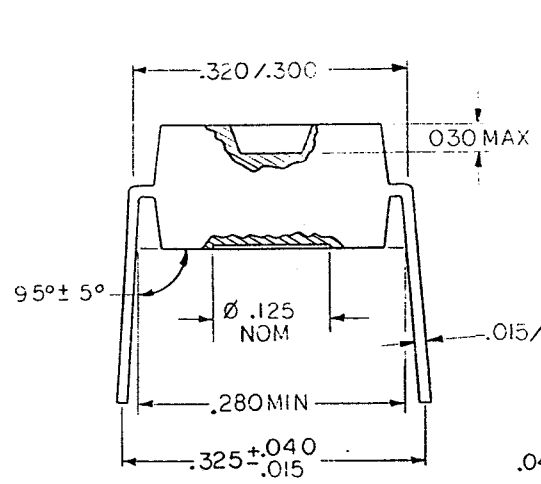
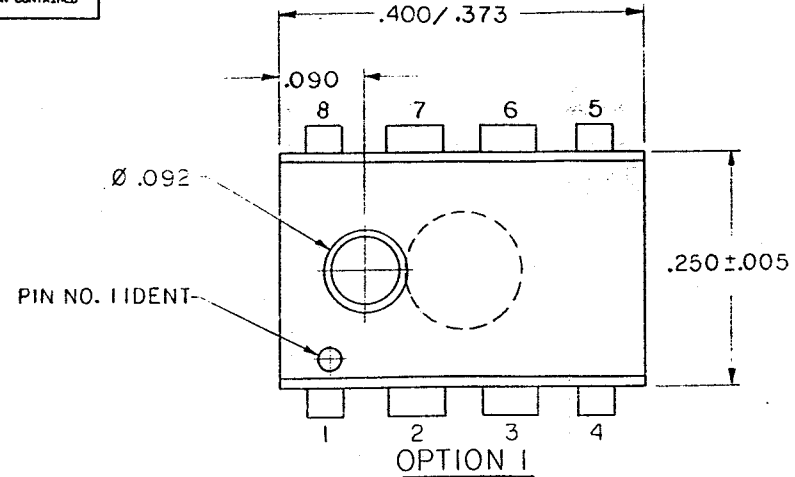
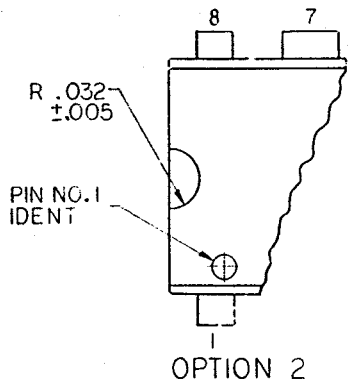


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REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
F	LEAD SPREAD WAS .325- <sup>1.025</sup> .015 REDRAW	01695	6-27-84	OC/ W



1 STANDARD LEAD FINISH;  
200μ" MINIMUM LEAD TIN 37/63  
ON ALLOY 42 OR EQUIVALENT.

NOTES: UNLESS OTHERWISE SPECIFIED

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES. TOLERANCES ARE: DECIMALS: .XX ± .XXX ± .XXXX ± ANGLES: N/A	APPROVALS	DATE	NATIONAL SEMICONDUCTOR CORPORATION 2900 Semiconductor Drive, Santa Clara, Calif. 95051		
	DRINK O CAMPBELL ENGR. CHK. APPROVAL MATERIAL FINISH DO NOT SCALE DRAWING	6-28-84 7-12-84 7-16-84 N/A		8 LEAD MOLDED DIP (N)	
	PROJECTION	SCALE	SIZE	DRAWING NUMBER	REV
		10X1	C	MKT-N08E	F
		FORMERLY:	SHEET	OF	